

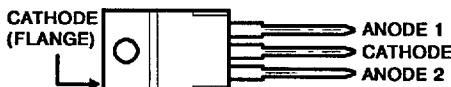
**Dual 8A High-Speed, High-Efficiency
Epitaxial Silicon Rectifiers**

August 1991

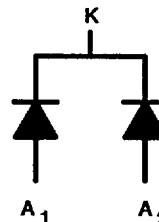
T-23-07

Features

- Ultrafast Recovery Time ($t_{rr} < 35\text{ns}$)
- Low Forward Voltage
- Low Thermal Resistance
- Planar Design
- Wire-Bonded Construction

PackageTO-220AB
TOP VIEW**Applications**

- General Purpose
- Power Switching Circuits to 100kHz
- Full-Wave Rectification

Symbol**Description**

The RURD810, RURD815, RURD820 are low forward voltage drop ultrafast rectifiers ($t_{rr} < 35\text{ns}$). They use a glass passivated ion-implanted, epitaxial construction.

These devices are intended for use as output rectifiers and flywheel diodes in a variety of high frequency pulse width modulated and switching regulators. Their low stored charge and attendant fast reverse recovery behavior minimize electrical noise generation and in many circuits markedly reduce the turn-on dissipation of the associated power switching transistors.

All are supplied in TO-220AB plastic packages.

Absolute Maximum Ratings ($T_C = +25^\circ\text{C}$)

	RURD810	RURD815	RURD820
Peak Repetitive Reverse Voltage.....	V _{RRM}	100V	150V
Average Rectified Forward Current			
$T_A = 25^\circ\text{C}$ (No Heat Sink)	I _{F(AV)}	3A	3A
$T_A = 250^\circ\text{C}$ (With Heat Sink)*	I _{F(AV)}	8A	8A
$T_A = 125^\circ\text{C}$	I _{F(AV)}	8A	8A
Nonrepetitive Peak Surge Current	I _{FSM}	100A	100A
(8.3ms, $\frac{1}{2}$ cycle)			
Operating and Storage Temperature	T _{STG} , T _J	-55°C to +175°C	-55°C to +175°C
Maximum Lead Temperature During Solder	T _L	260°C	260°C
(At distance $> \frac{1}{8}$ " (3.17mm) from case or 10s max)			260°C

*Wakefield type 295 heat sink with convection cooling.

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ULTRA-FAST
RECTIFIERS

Specifications RURD810, RURD815, RURD820

HARRIS SEMICOND SECTOR 56E D ■ 4302271 0042399 967 ■ HAS
Electrical Characteristics ($T_C = +25^\circ\text{C}$) Unless Otherwise Specified.

SYMBOL	TEST CONDITION	LIMITS									T-23-07	
		RURD810			RURD815			RURD820				
		MIN	Typ	MAX	MIN	Typ	MAX	MIN	Typ	MAX		
VF	$I_F = 8\text{A}$ $T_C = +150^\circ\text{C}$	-	-	0.83	-	-	0.83	-	-	0.85	V	
	$I_F = 8\text{A}$ $T_C = +25^\circ\text{C}$	-	-	0.975	-	-	0.975	-	-	1	V	
IR @ $T_C = +150^\circ\text{C}$	$V_R = 100\text{V}$	-	-	250	-	-	-	-	-	-	μA	
	$V_R = 150\text{V}$	-	-	-	-	-	250	-	-	-	μA	
	$V_R = 200\text{V}$	-	-	-	-	-	-	-	-	250	μA	
IR @ $T_C = +25^\circ\text{C}$	$V_R = 100\text{V}$	-	-	5	-	-	-	-	-	-	μA	
	$V_R = 150\text{V}$	-	-	-	-	-	5	-	-	-	μA	
	$V_R = 200\text{V}$	-	-	-	-	-	-	-	-	5	μA	
t _{rr}	$I_F = 8\text{A}^*$	-	-	35	-	-	35	-	-	35	ns	
R _{θjc}		-	-	2.25	-	-	2.25	-	-	2.25	°C/W	
R _{θja}		-	-	60	-	-	60	-	-	60	°C/W	
C _J	$V_R = 10\text{V}$ $I_F = 0\text{A}$	-	40	-	-	40	-	-	40	-	pF	

* $dI_F/dt = 40\text{A}/\mu\text{s}$, I_{RM} (rec) < 1A, $I_{RR} = 0.25\text{A}$.

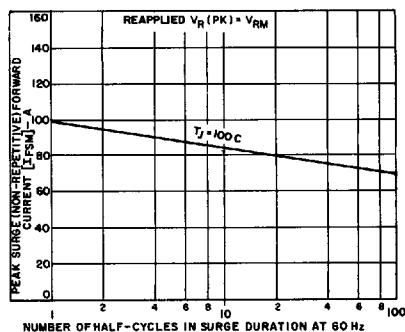


FIGURE 1. PEAK SURGE FORWARD CURRENT
vs SURGE DURATION

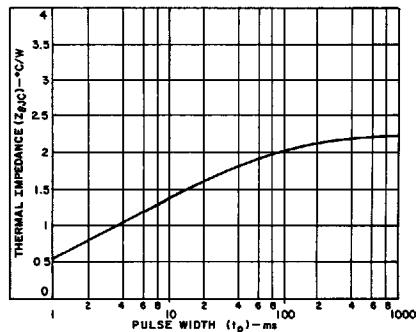


FIGURE 2. THERMAL IMPEDANCE vs PULSE WIDTH
(PER JUNCTION)

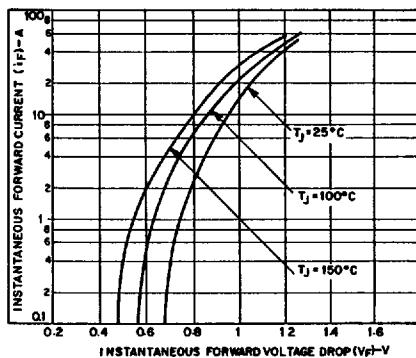


FIGURE 3. TYPICAL FORWARD CURRENT
vs FORWARD VOLTAGE DROP

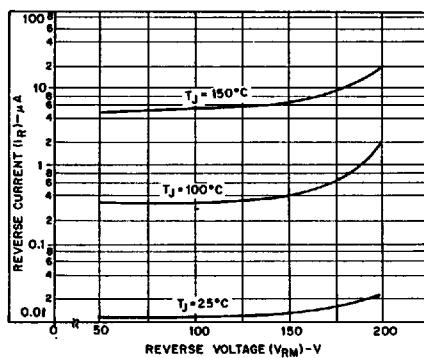


FIGURE 4. TYPICAL REVERSE CURRENT vs VOLTAGE